



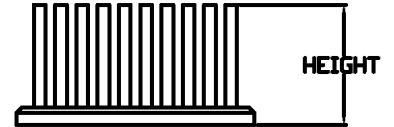
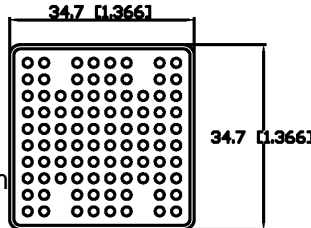
# Model : CMBA023535 Series



## BGA Heat Sink Specification

For 35x35 Chip set

1. Material : Al 6063
2. Dimension :
  - Foot print : 35x35mm
  - Height : 12,15,18,21,23,28,33 mm
  - Base (thickness) : 2.6mm



3. Finish: Black Anodize
4. Chip set package thickness and clip color
  - 3.3+/-0.25mm - Yellow clip
  - 1.7+/-0.25mm - Blue clip
  - 0.8+/-0.25mm - Orange clip
5. Accessory :
  - Clip : Plastic (UL94-V0)
  - Thermal pad : T710 or others



## Performance

Heat Source (LxW)	15x15
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